

PKG. CODES
[S8+2]
[S8+2C]
[S8+4]
[S8+4C]
[S8+5]
[S8M+5]
[S8+6F]
[S8+7F]
[S8+8F]
[S8+10F]
[S8+11F]
[S8+16F]
[S8MK+1]
[S8+19F]
[S8+20]
[S8+21]
[S8MS+22]
[S8+22]
[S8+23]
[S8MS+24]

NOTES:

1. REFERENCE PKG. OUTLINE: 21-0041.
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.
5. ALL DIMENSIONS ARE IN MM.

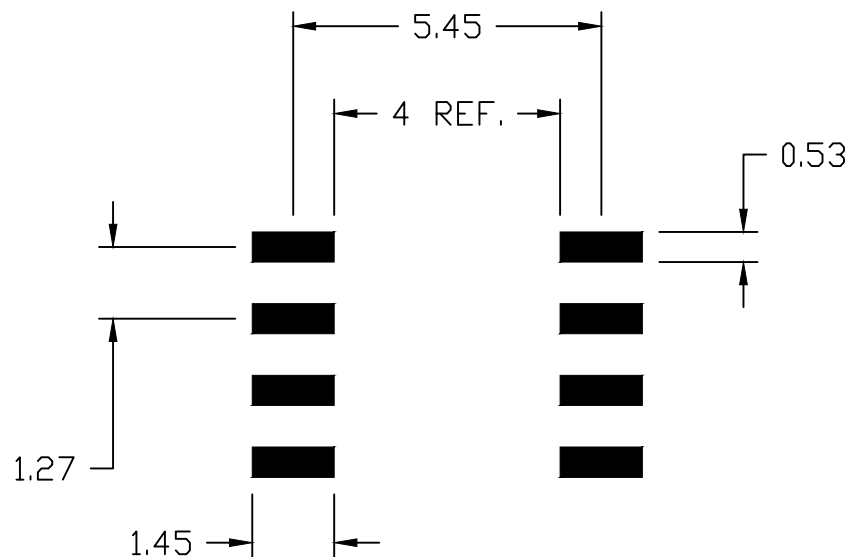
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This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at <http://www.maxim-ic.com/support> for further questions.

TITLE: PACKAGE LAND PATTERN, [S8] 0.150" SOIC, 8 LEADS		
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OPTION FOR IMPROVED HV ISOLATION
 (CLEARANCE/CREEPAGE OF 4MM)



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